

Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)} \text{ Max}$	I_D $T_A = +25^\circ\text{C}$
24V	7m Ω @ $V_{GS} = 4.5\text{V}$	11.0A
	7.8m Ω @ $V_{GS} = 4.0\text{V}$	10.8A
	8.2m Ω @ $V_{GS} = 3.7\text{V}$	10.6A
	9.5m Ω @ $V_{GS} = 3.1\text{V}$	10.5A
	10.5m Ω @ $V_{GS} = 2.5\text{V}$	10.0A

Description

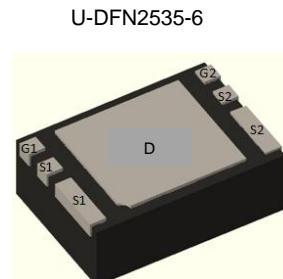
This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

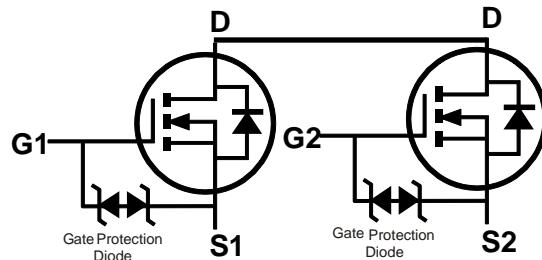
- Power Management Functions
- Battery Pack
- Load Switch



ESD PROTECTED



Bottom View



Equivalent Circuit

Ordering Information (Note 4)

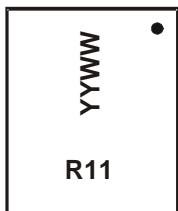
Part Number	Case	Packaging
DMN2010UDZ-7	U-DFN2535-6	3,000 / Tape & Reel

Notes:

- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

U-DFN2535-6



R11 = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Last Digit of Year (ex: 15 for 2015)
 WW = Week Code (01 to 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	24	V
Gate-Source Voltage			V_{GSS}	± 8	V
Continuous Drain Current (Note 6) $V_{GS} = 4.5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +70^\circ\text{C}$	I_D	11 9	A
Maximum Continuous Body Diode Forward Current (Note 6)			I_S	2	A
Pulsed Drain Current (380 μs Pulse, Duty Cycle = 1%)			I_{DM}	65	A
Avalanche Current (Note 7) $L = 0.1\text{mH}$			I_{AS}	34	A
Avalanche Energy (Note 7) $L = 0.1\text{mH}$			E_{AS}	57	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^\circ\text{C}$	P_D	0.7	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R_{0JA}	184	$^\circ\text{C}/\text{W}$
Total Power Dissipation (Note 6)	$T_A = +25^\circ\text{C}$	P_D	1.6	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R_{0JA}	78	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Case		R_{0JC}	16.4	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV_{DSS}	24	-	-	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = +25^\circ\text{C}$	I_{DSS}	-	-	1.0	μA	$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	-	-	± 10	μA	$V_{GS} = \pm 8\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(TH)}$	0.3	-	1.5	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	-	-	7	$\text{m}\Omega$	$V_{GS} = 4.5\text{V}, I_D = 5.5\text{A}$
			-	7.8		$V_{GS} = 4.0\text{V}, I_D = 5.5\text{A}$
			-	8.2		$V_{GS} = 3.7\text{V}, I_D = 5.5\text{A}$
			-	9.5		$V_{GS} = 3.1\text{V}, I_D = 5.5\text{A}$
			-	10.5		$V_{GS} = 2.5\text{V}, I_D = 5.5\text{A}$
Diode Forward Voltage	V_{SD}	-	0.7	1.2	V	$V_{GS} = 0\text{V}, I_S = 1\text{A}$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C_{iss}	-	2,665	-	pF	$V_{DS} = 10\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	-	323	-	pF	
Reverse Transfer Capacitance	C_{rss}	-	311	-	pF	
Gate Resistance	R_g	-	1.1	-	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge ($V_{GS} = 4.5\text{V}$)	Q_g	-	33.2	-	nC	$V_{DS} = 10\text{V}, I_D = 5.5\text{A}$
Gate-Source Charge	Q_{qs}	-	3.6	-	nC	
Gate-Drain Charge	Q_{gd}	-	5.6	-	nC	
Turn-On Delay Time	$t_{D(ON)}$	-	7.5	-	ns	$V_{DD} = 16\text{V}, I_D = 5.5\text{A}, V_{GS} = 4.5\text{V}, R_G = 6\Omega$
Turn-On Rise Time	t_R	-	20	-	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	-	93	-	ns	
Turn-Off Fall Time	t_F	-	49	-	ns	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

7. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^\circ\text{C}$.

8. Short duration pulse test used to minimize self-heating effect.

9. Guaranteed by design. Not subject to product testing.

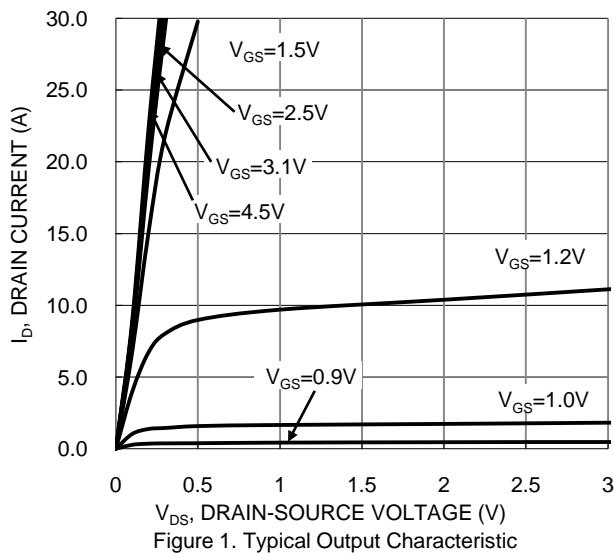


Figure 1. Typical Output Characteristic

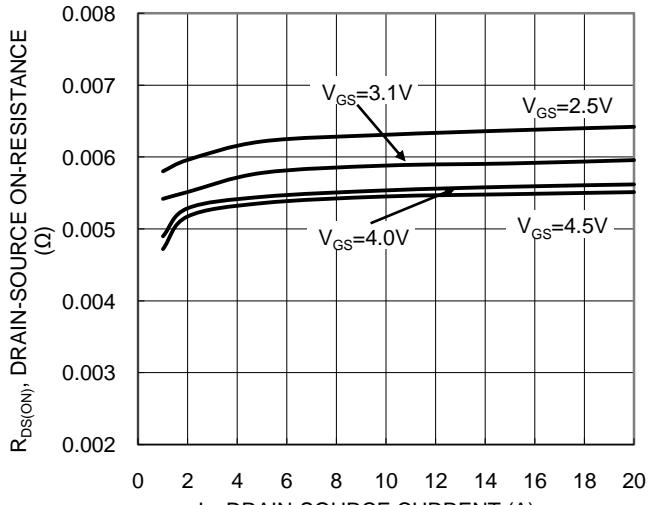


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

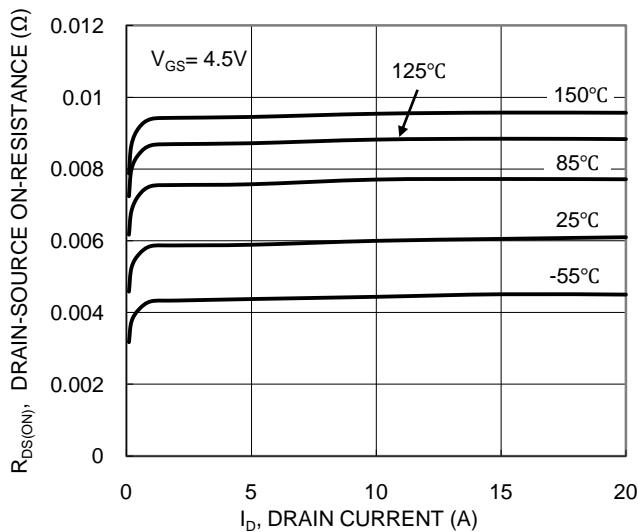


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

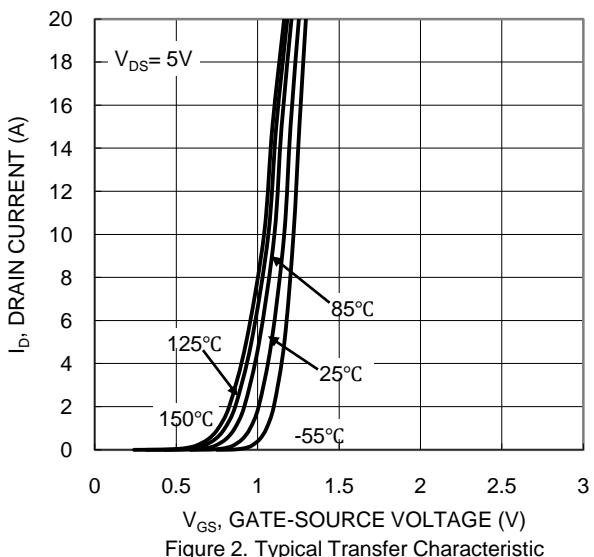


Figure 2. Typical Transfer Characteristic

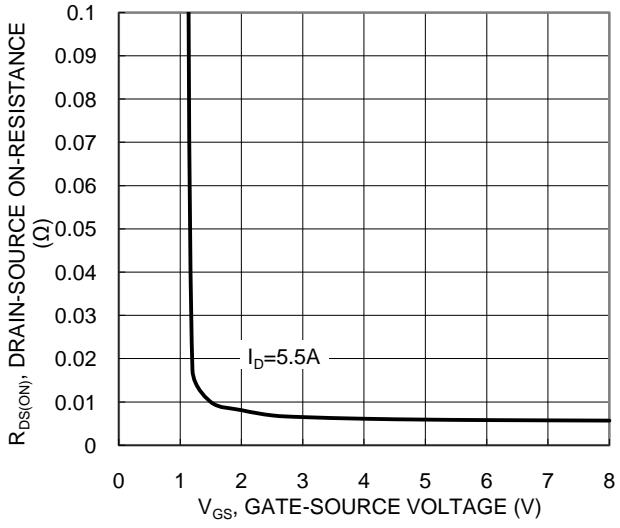


Figure 4. Typical Transfer Characteristic

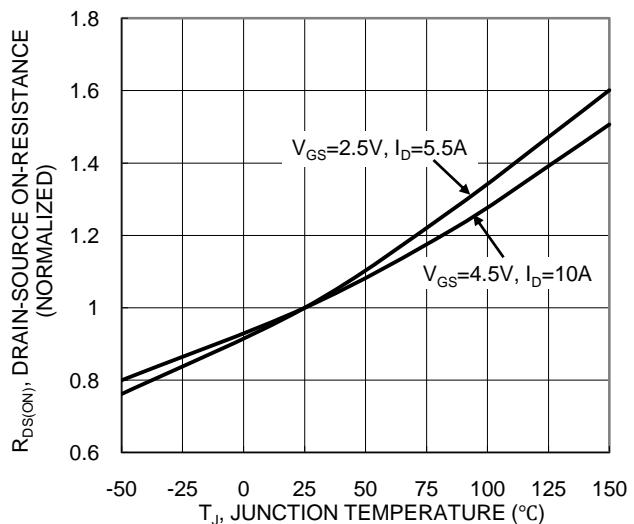
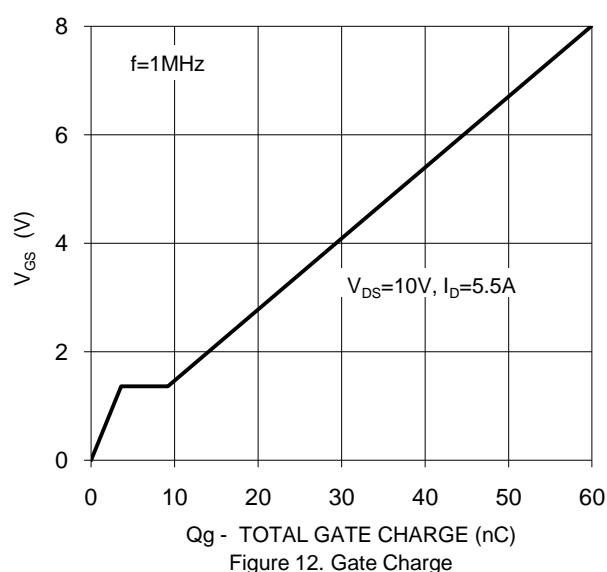
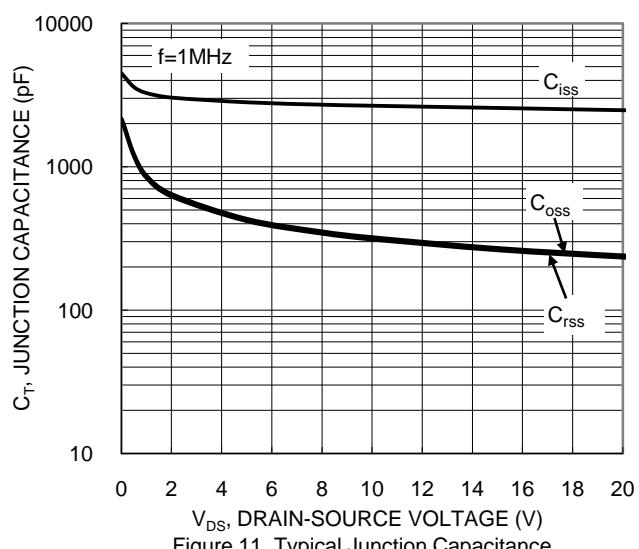
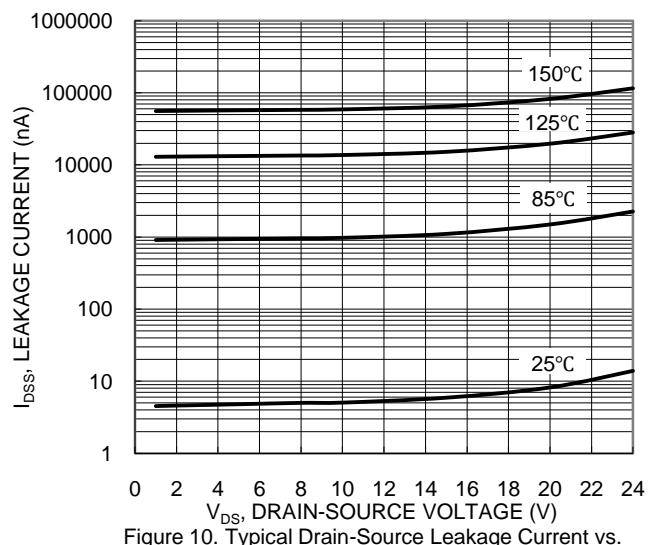
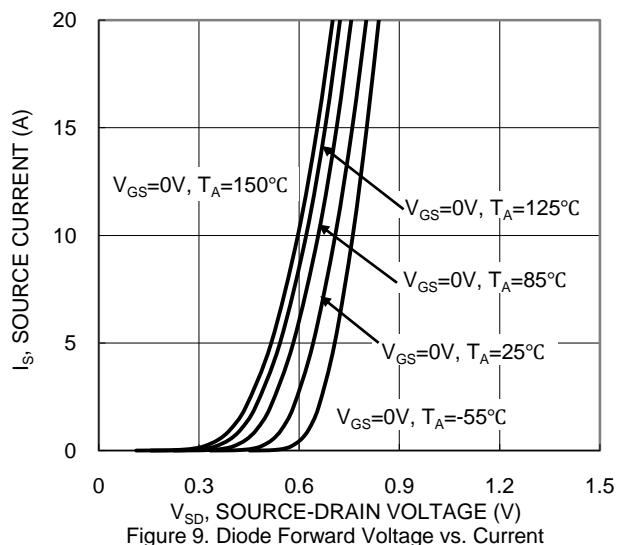
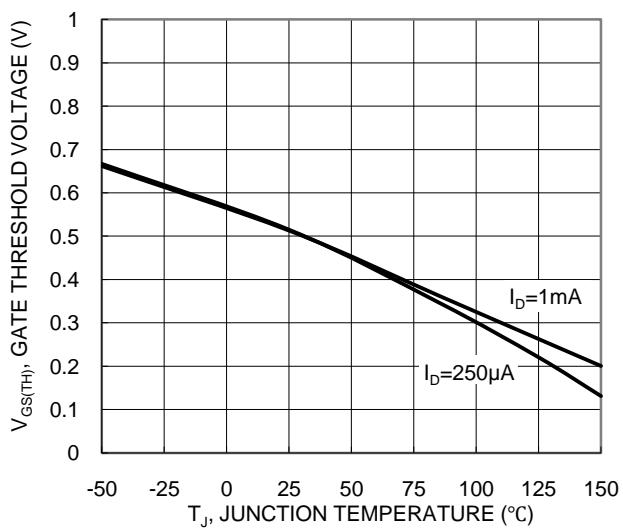
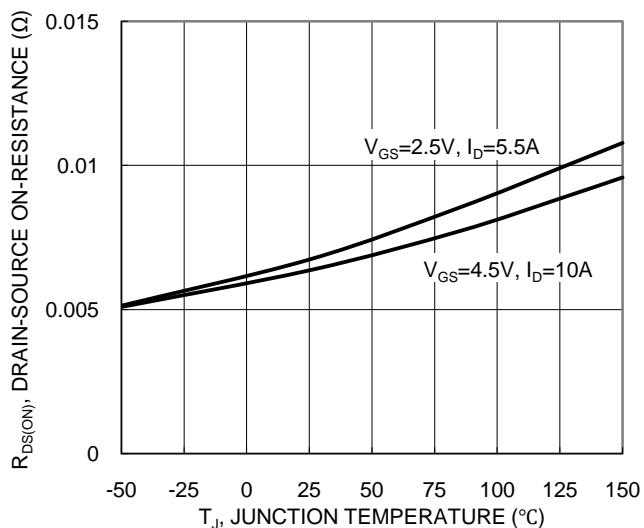


Figure 6. On-Resistance Variation with Temperature



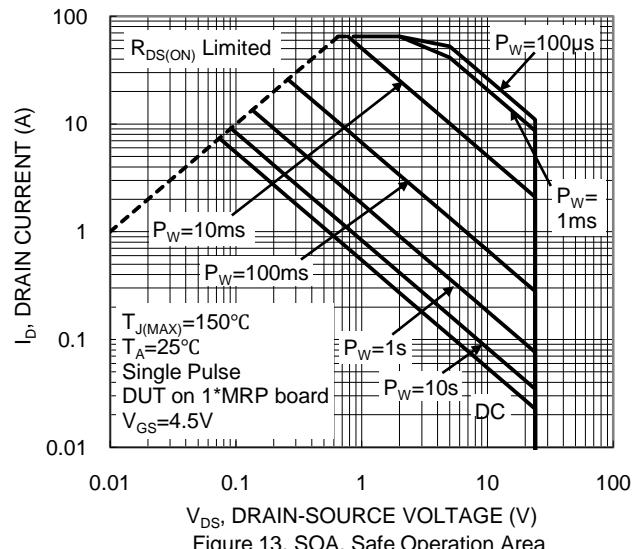


Figure 13. SOA, Safe Operation Area

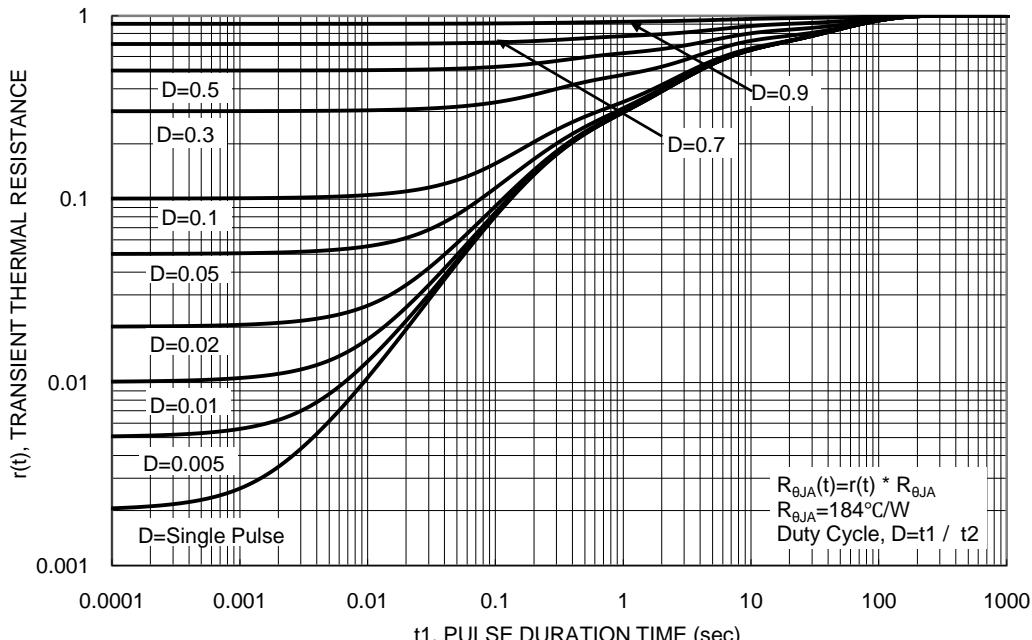
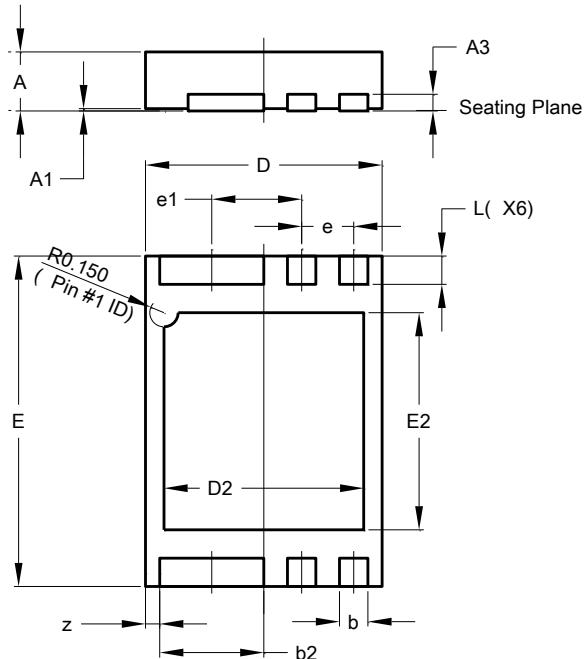


Figure 14. Transient Thermal Resistance

Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.

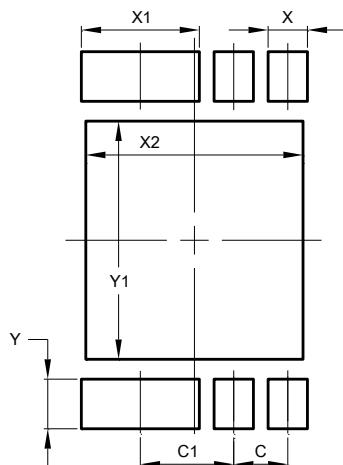


U-DFN2535-6 (Type B)			
Dim	Min	Max	Typ
A	0.50	0.60	-
A1	0.00	0.05	0.02
A3	-	-	0.127
b	0.25	0.35	0.30
b2	1.05	1.15	1.10
D	2.45	2.55	2.50
D2	2.01	2.21	2.11
E	3.45	3.55	3.50
E2	2.20	2.40	2.30
e	-	-	0.55
e1	-	-	0.95
L	0.25	0.35	0.30
z	-	-	0.15

All Dimensions in mm

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.550
C1	0.950
X	0.400
X1	1.200
X2	2.210
Y	0.500
Y1	2.400

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